



OPT209

PHOTODIODE WITH ON-CHIP AMPLIFIER

FEATURES

- **PHOTODIODE SIZE: 0.090 x 0.090 inch (2.29 x 2.29mm)**
- **1M Ω FEEDBACK RESISTOR**
- **HIGH RESPONSIVITY: 0.45A/W (650nm)**
- **LOW DARK ERRORS: 2mV**
- **BANDWIDTH: 16kHz**
- **WIDE SUPPLY RANGE: ± 2.25 to ± 18 V**
- **LOW QUIESCENT CURRENT: 400 μ A**
- **TRANSPARENT 8-PIN DIP**

APPLICATIONS

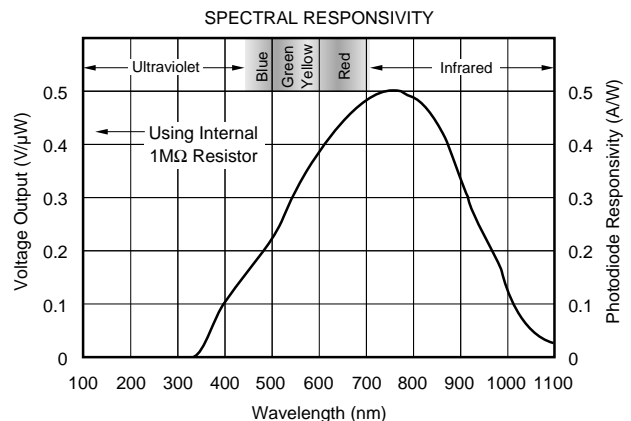
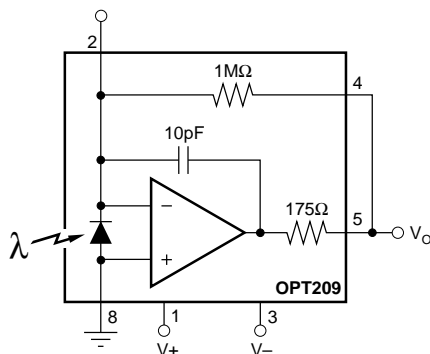
- **MEDICAL INSTRUMENTATION**
- **LABORATORY INSTRUMENTATION**
- **POSITION AND PROXIMITY SENSORS**
- **PHOTOGRAPHIC ANALYZERS**
- **SMOKE DETECTORS**

DESCRIPTION

The OPT209 is an opto-electronic integrated circuit containing a photodiode and transimpedance amplifier on a single dielectrically isolated chip. The transimpedance amplifier consists of a precision FET-input op amp and an on-chip metal film resistor. The 0.09 x 0.09 inch photodiode is operated at zero bias for excellent linearity and low dark current.

The integrated combination of photodiode and transimpedance amplifier on a single chip eliminates the problems commonly encountered in discrete designs such as leakage current errors, noise pick-up and gain peaking due to stray capacitance.

The OPT209 operates over a wide supply range (± 2.25 to ± 18 V) and supply current is only 400 μ A. It is packaged in a transparent plastic 8-pin DIP, specified for the 0 $^{\circ}$ C to 70 $^{\circ}$ C temperature range.



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Tel: (520) 746-1111 • Twx: 910-952-1111 • Cable: BBRCORP • Telex: 066-6491 • FAX: (520) 889-1510 • Immediate Product Info: (800) 548-6132

SPECIFICATIONS

ELECTRICAL

$T_A = +25^\circ\text{C}$, $V_S = \pm 15\text{V}$, $\lambda = 650\text{nm}$, internal $1\text{M}\Omega$ feedback resistor, unless otherwise noted.

PARAMETER	CONDITIONS	OPT209P			UNITS
		MIN	TYP	MAX	
RESPONSIVITY Photodiode Current Voltage Output vs Temperature Unit-to-Unit Variation Nonlinearity ⁽¹⁾ Photodiode Area	650nm 650nm 650nm FS Output = 10V (0.090 x 0.090in) (2.29 x 2.29mm)		0.45 0.45 100 ± 5 0.01 0.008 5.2		A/W V/ μW ppm/ $^\circ\text{C}$ % % of FS in ² mm ²
DARK ERRORS, RTO⁽²⁾ Offset Voltage, Output vs Temperature vs Power Supply Voltage Noise	$V_S = \pm 2.25\text{V}$ to $\pm 18\text{V}$ Measured BW = 0.1 to 100kHz		± 0.5 ± 10 10 350	± 2 100	mV $\mu\text{V}/^\circ\text{C}$ $\mu\text{V}/\text{V}$ $\mu\text{V}/\text{rms}$
RESISTOR—1MΩ Internal Resistance Tolerance vs Temperature			1 ± 0.5 50	± 2	M Ω % ppm/ $^\circ\text{C}$
FREQUENCY RESPONSE Bandwidth, Large or Small-Signal, -3dB Rise Time, 10% to 90% Settling Time, 1% 0.1% 0.01% Overload Recovery Time (to 1%)	FS to Dark FS to Dark FS to Dark 100% Overdrive, $V_S = \pm 15\text{V}$ 100% Overdrive, $V_S = \pm 5\text{V}$ 100% Overdrive, $V_S = \pm 2.25\text{V}$		16 22 60 85 100 44 100 240		kHz μs μs μs μs μs μs μs
OUTPUT Voltage Output Capacitive Load, Stable Operation Short-Circuit Current	$R_L = 10\text{k}\Omega$ $R_L = 5\text{k}\Omega$	(V+) - 1.25 (V+) - 2	(V+) - 1 (V+) - 1.5 1 ± 18		V V nF mA
POWER SUPPLY Specified Operating Voltage Operating Voltage Range Quiescent Current	$V_O = 0$	± 2.25	± 15 ± 400	± 18 ± 500	V V μA
TEMPERATURE RANGE Specification, Operating Storage Thermal Resistance, θ_{JA}		0 -25		+70 +85 100	$^\circ\text{C}$ $^\circ\text{C}$ $^\circ\text{C}/\text{W}$

NOTES: (1) Deviation in percent of full scale from best-fit straight line. (2) Referred to Output. Includes all error sources.

PHOTODIODE SPECIFICATIONS

$T_A = +25^\circ\text{C}$, unless otherwise noted.

PARAMETER	CONDITIONS	Photodiode of OPT209			UNITS
		MIN	TYP	MAX	
Photodiode Area	(0.090 x 0.090in) (2.29 x 2.29mm)		0.008 5.1		in ² mm ²
Current Responsivity	650nm		0.45		A/W
Dark Current vs Temperature	$V_D = 0\text{V}^{(1)}$		500 doubles every 10°C		fA
Capacitance	$V_D = 0\text{V}^{(1)}$		600		pF

NOTE: (1) Voltage Across Photodiode.

SPECIFICATIONS (CONT)

ELECTRICAL

Op Amp Section of OPT209¹⁾

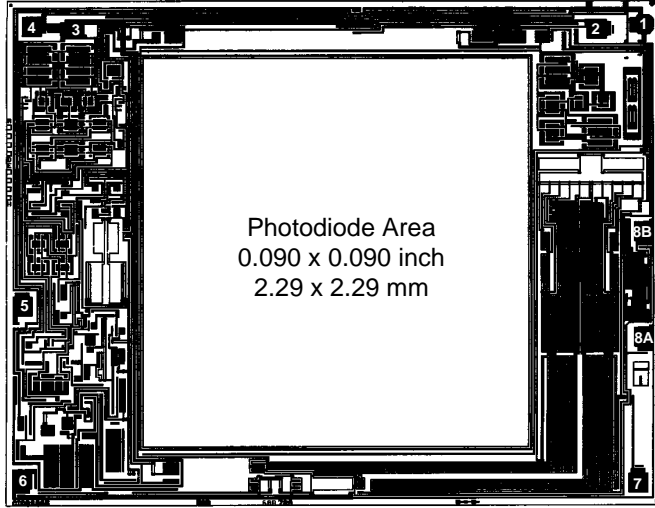
T_A = +25°C, V_S = ±15V, unless otherwise noted.

PARAMETER	CONDITIONS	OPT209 Op Amp			UNITS
		MIN	TYP	MAX	
INPUT Offset Voltage vs Temperature vs Power Supply Input Bias Current vs Temperature	V _S = ±2.25V to ±18V		±0.5 ±5 10 1 doubles every 10°C		mV μV/°C μV/V pA
NOISE Input Voltage Noise Voltage Noise Density, f=10Hz f=100Hz f=1kHz Current Noise Density, f=1kHz			30 25 15 0.8		nV/√Hz nV/√Hz nV/√Hz fA/√Hz
INPUT VOLTAGE RANGE Common-Mode Input Range Common-Mode Rejection			±14.4 106		V dB
INPUT IMPEDANCE Differential Common-Mode			10 ¹² 3 10 ¹² 3		Ω pF Ω pF
OPEN-LOOP GAIN Open-Loop Voltage Gain			120		dB
FREQUENCY RESPONSE Gain-Bandwidth Product Slew Rate Settling Time 0.1% 0.01%			4 6 4 5		MHz V/μs μs μs
OUTPUT Voltage Output Short-Circuit Current	R _L = 10kΩ R _L = 5kΩ	(V+) – 1.25 (V+) – 2	(V+) – 1 (V+) – 1.5 ±18		V V mA
POWER SUPPLY Specified Operating Voltage Operating Voltage Range Quiescent Current	I _O = 0	±2.25	±15 ±400	±18 ±500	V V μA

NOTE: (1) Op amp specifications provided for information and comparison only.

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DICE INFORMATION



OPT209 DIE TOPOGRAPHY

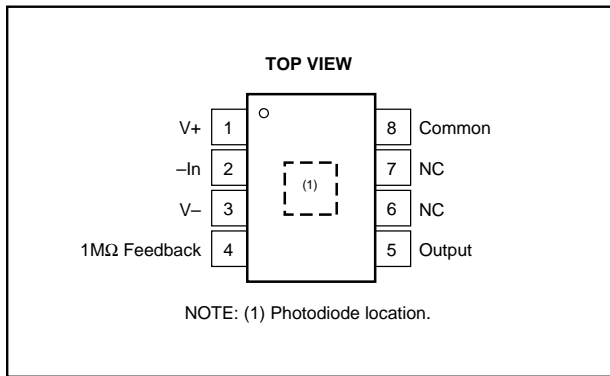
PAD	FUNCTION
1	V+
2	-In
3	V-
4	1MΩ Feedback
5	Output
6	NC
7	NC
8A, 8B	Common

NC: No Connection. Pads 8A and 8B must both be connected to common. Substrate Bias: The substrate is electrically connected to internal circuitry. Do not make electrical connection to the substrate.

MECHANICAL INFORMATION

	MILS (0.001")	MILLIMETERS
Die Size	154 x 120 ±5	3.91 x 3.05 ±0.13
Die Thickness	20 ±3	0.51 ±0.08
Min. Pad Size	4 x 4	0.1 x 0.1
Backing		None

PIN CONFIGURATION



ELECTROSTATIC DISCHARGE SENSITIVITY

This integrated circuit can be damaged by ESD. Burr-Brown recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

MOISTURE SENSITIVITY AND SOLDERING

Clear plastic does not contain the structural-enhancing fillers used in black plastic molding compound. As a result, clear plastic is more sensitive to environmental stress than black plastic. This can cause difficulties if devices have been stored in high humidity prior to soldering. The rapid heating during soldering can stress wire bonds and cause failures. Prior to soldering, it is recommended that devices be baked-out at 85°C for 24 hours.

The fire-retardant fillers used in black plastic are not compatible with clear molding compound. The OPT209 cannot meet flammability test, UL-94.

ABSOLUTE MAXIMUM RATINGS

Supply Voltage	±18V
Input Voltage Range (Common Pin)	±V _S
Output Short-Circuit (to ground)	Continuous
Operating Temperature	-25°C to +85°C
Storage Temperature	-25°C to +85°C
Junction Temperature	+85°C
Lead Temperature (soldering, 10s)	+300°C
(Vapor-Phase Soldering Not Recommended)	

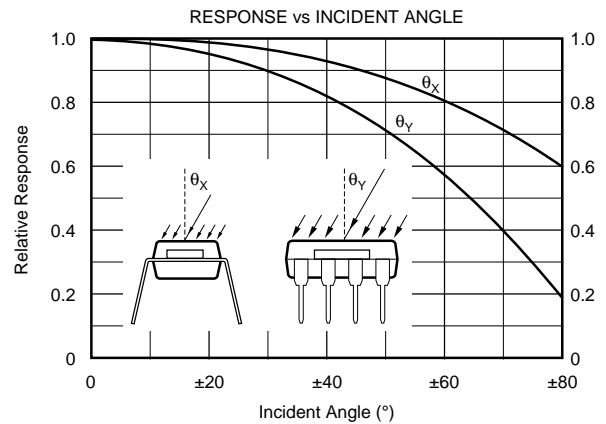
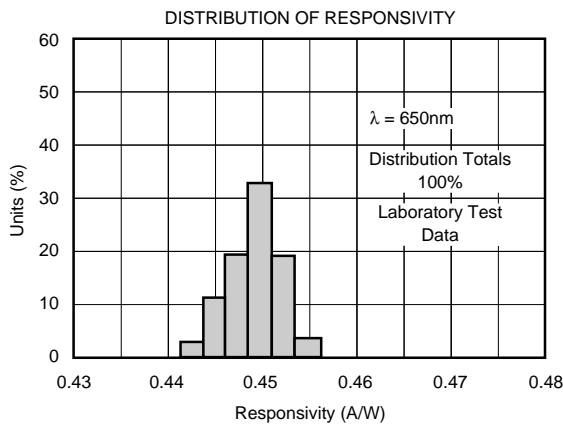
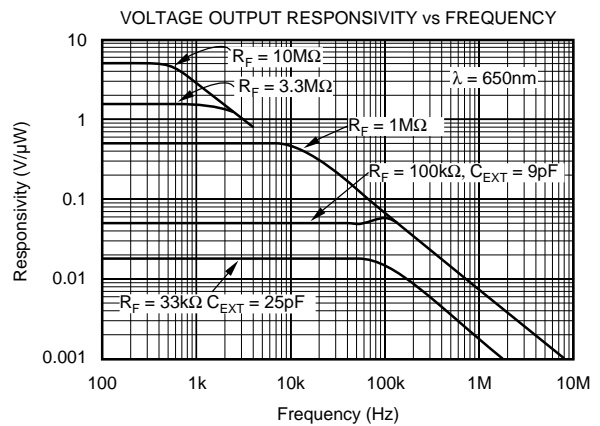
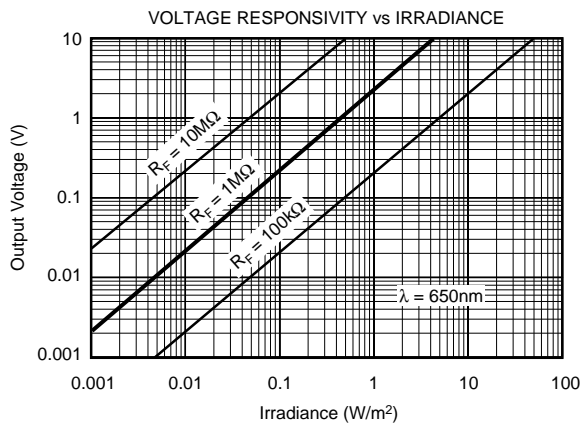
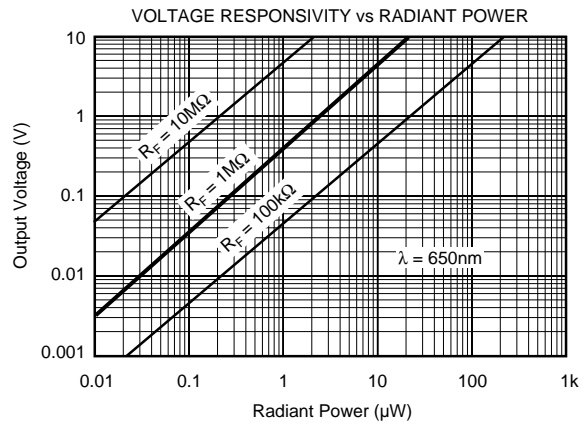
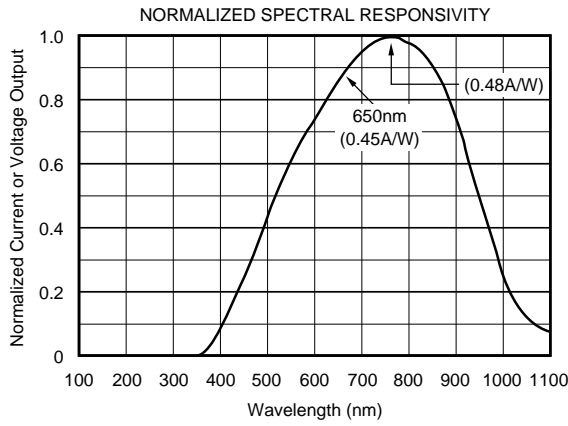
PACKAGE INFORMATION

MODEL	PACKAGE	PACKAGE DRAWING NUMBER ⁽¹⁾
OPT209P	8-Pin DIP	006-1

NOTE: (1) For detailed drawing and dimension table, please see end of data sheet, or Appendix D of Burr-Brown IC Data Book.

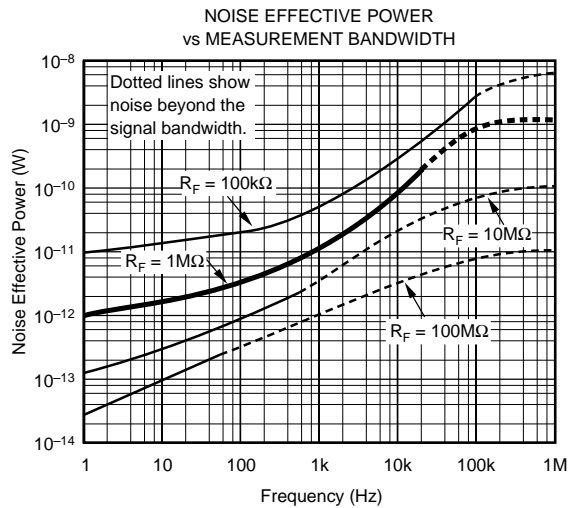
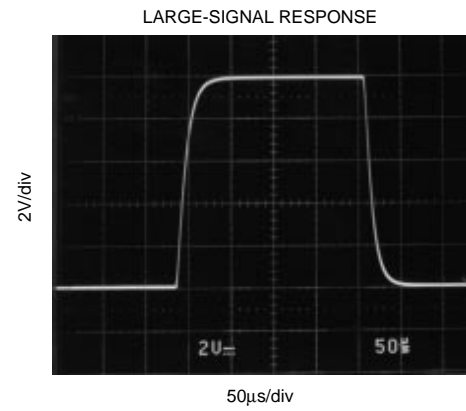
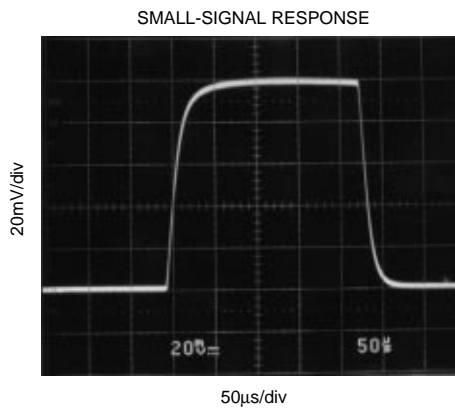
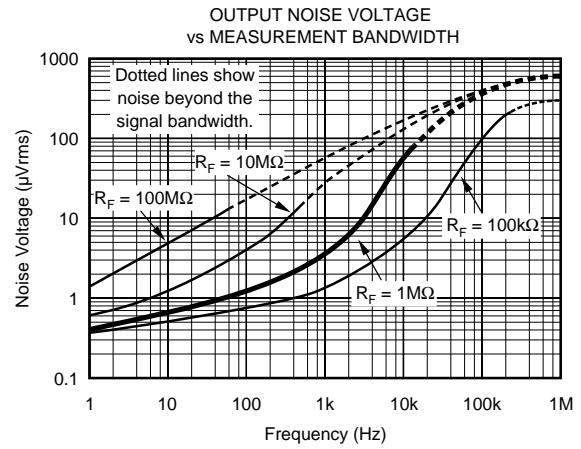
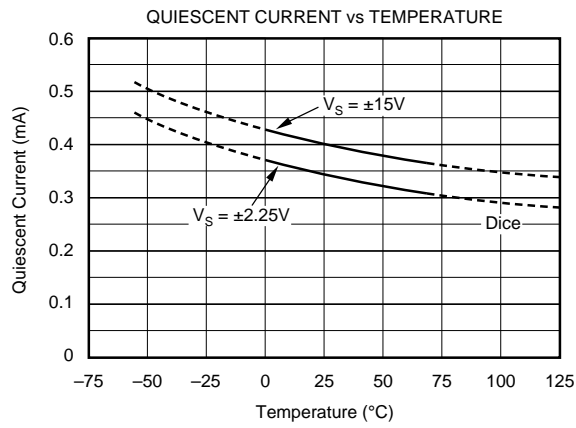
TYPICAL PERFORMANCE CURVES

At $T_A = +25^\circ\text{C}$, $V_S = \pm 15\text{V}$, $\lambda = 650\text{nm}$, unless otherwise noted.



TYPICAL PERFORMANCE CURVES (CONT)

At $T_A = +25^\circ\text{C}$, $V_S = \pm 15\text{V}$, $\lambda = 650\text{nm}$, unless otherwise noted.



APPLICATIONS INFORMATION

Figure 1 shows the basic connections required to operate the OPT209. Applications with high-impedance power supplies may require decoupling capacitors located close to the device pins as shown. Output is zero volts with no light and increases with increasing illumination.

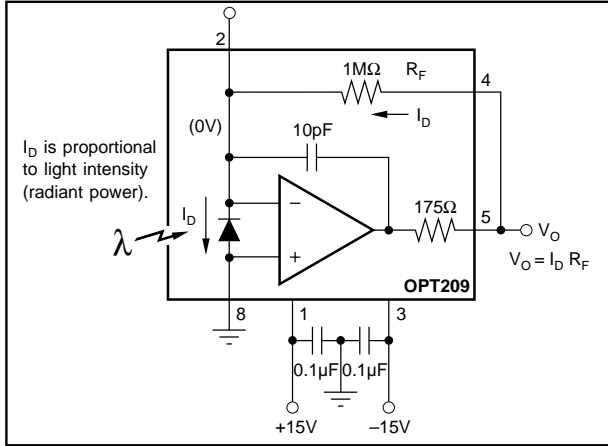


FIGURE 1. Basic Circuit Connections.

Photodiode current, I_D , is proportional to the radiant power or flux (in watts) falling on the photodiode. At a wavelength of 650nm (visible red) the photodiode Responsivity, R_P , is approximately 0.45A/W. Responsivity at other wavelengths is shown in the typical performance curve “Responsivity vs Wavelength.”

The typical performance curve “Output Voltage vs Radiant Power” shows the response throughout a wide range of radiant power. The response curve “Output Voltage vs Irradiance” is based on the photodiode area of $5.23 \times 10^{-6} \text{m}^2$.

The OPT209’s voltage output is the product of the photodiode current times the feedback resistor, ($I_D R_F$). The internal feedback resistor is laser trimmed to $1\text{M}\Omega \pm 2\%$. Using this resistor, the output voltage responsivity, R_V , is approximately 0.45V/ μW at 650nm wavelength.

An external resistor can be connected to set a different voltage responsivity. Best dynamic performance is achieved by connecting R_{EXT} in series (for $R_F > 1\text{M}\Omega$), or in parallel (for $R_F < 1\text{M}\Omega$), with the internal resistor as shown in Figure 2. These connections take advantage of on-chip capacitive guarding of the internal resistor, which improves dynamic performance. For values of R_F less than $1\text{M}\Omega$, an external capacitor, C_{EXT} , should be connected in parallel with R_F (see Figure 2). This capacitor eliminates gain peaking and prevents instability. The value of C_{EXT} can be read from the table in Figure 2.

LIGHT SOURCE POSITIONING

The OPT209 is 100% tested with a light source that uniformly illuminates the full area of the integrated circuit, including the op amp. Although all IC amplifiers are light-sensitive to some degree, the OPT209 op amp circuitry is designed to minimize this effect. Sensitive junctions are shielded with

metal, and differential stages are cross-coupled. Furthermore, the photodiode area is very large relative to the op amp input circuitry making these effects negligible.

If your light source is focused to a small area, be sure that it is properly aimed to fall on the photodiode. If a narrowly focused light source were to miss the photodiode area and fall only on the op amp circuitry, the OPT209 would not perform properly. The large (0.090 x 0.090 inch) photodiode area allows easy positioning of narrowly focused light sources. The photodiode area is easily visible—it appears very dark compared to the surrounding active circuitry.

The incident angle of the light source also affects the apparent sensitivity in uniform irradiance. For small incident angles, the loss in sensitivity is simply due to the smaller effective light gathering area of the photodiode (proportional to the cosine of the angle). At a greater incident angle, light is diffused by the side of the package. These effects are shown in the typical performance curve “Response vs Incident Angle.”

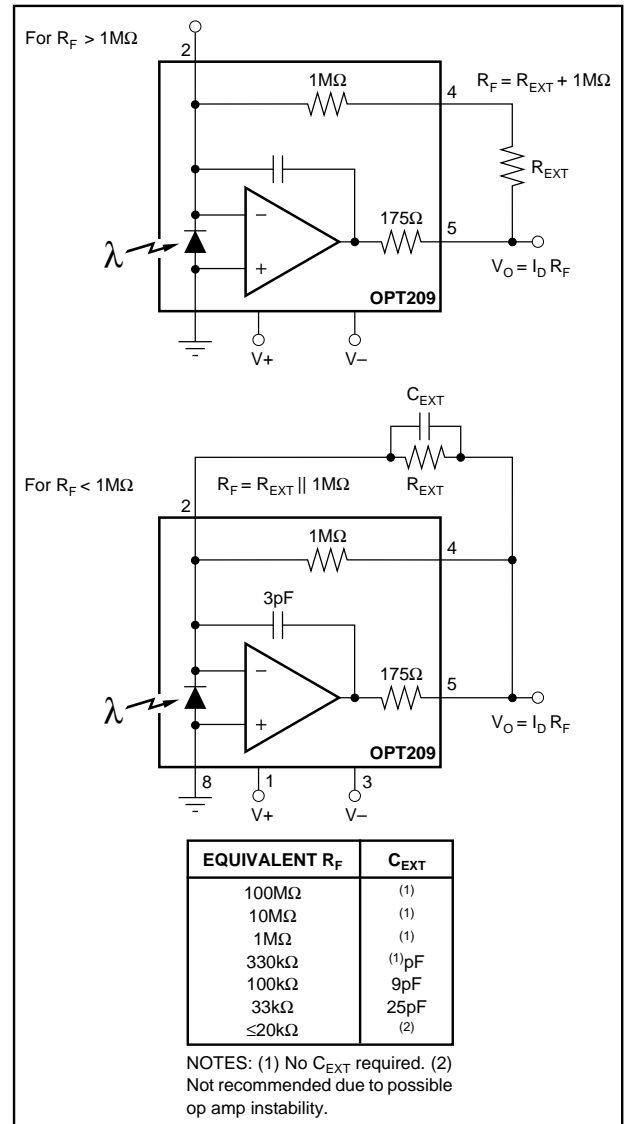


FIGURE 2. Using External Feedback Resistor.

DARK ERRORS

The dark errors in the specification table include all sources. The dominant error source is the input offset voltage of the op amp. Photodiode dark current and input bias current of the op amp are in the 2pA range and contribute virtually no offset error at room temperature. Dark current and input bias current double for each 10°C above 25°C. At 70°C, the error current can be approximately 100pA. This would produce a 1mV offset with $R_F = 10M\Omega$. The OPT209 is useful with feedback resistors of 100MΩ or greater at room temperature. The dark output voltage can be trimmed to zero with the optional circuit shown in Figure 3.

When used with very large feedback resistors, tiny leakage currents on the circuit board can degrade the performance of the OPT209. Careful circuit board design and clean assembly procedures will help achieve best performance. A “guard ring” on the circuit board can help minimize leakage to the critical non-inverting input (pin 2). This guard ring should encircle pin 2 and connect to Common, pin 8.

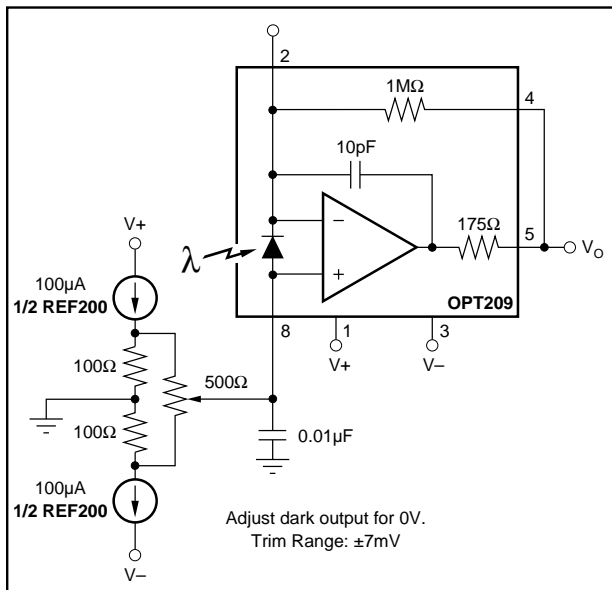


FIGURE 3. Dark Error (Offset) Adjustment Circuit.

LINEARITY PERFORMANCE

Current output of the photodiode is very linear with radiant power throughout a wide range. Nonlinearity remains below approximately 0.01% up to 100μA photodiode current. The photodiode can produce output currents of 10mA or greater with high radiant power, but nonlinearity increases to several percent in this region.

This very linear performance at high radiant power assumes that the full photodiode area is uniformly illuminated. If the light source is focused to a small area of the photodiode, nonlinearity will occur at lower radiant power.

DYNAMIC RESPONSE

Using the internal 1MΩ resistor, the dynamic response of the photodiode/op amp combination can be modeled as a

simple R/C circuit with a -3dB cutoff frequency of 16kHz. This yields a rise time of approximately 22μs (10% to 90%). Dynamic response is not limited by op amp slew rate. This is demonstrated by the dynamic response oscilloscope photographs showing virtually identical large-signal and small-signal response.

Dynamic response will vary with feedback resistor value as shown in the typical performance curve “Voltage Output Responsivity vs Frequency.” Rise time (10% to 90%) will vary according to the -3dB bandwidth produced by a given feedback resistor value—

$$t_R \approx \frac{0.35}{f_C} \quad (1)$$

where:

t_R is the rise time (10% to 90%)

f_C is the -3dB bandwidth

NOISE PERFORMANCE

Noise performance of the OPT209 is determined by the op amp characteristics in conjunction with the feedback components and photodiode capacitance. The typical performance curve “Output Noise Voltage vs Measurement Bandwidth” shows how the noise varies with R_F and measured bandwidth (1Hz to the indicated frequency). The signal bandwidth of the OPT209 is indicated on the curves. Noise can be reduced by filtering the output with a cutoff frequency equal to the signal bandwidth.

Output noise increases in proportion to the square-root of the feedback resistance, while responsivity increases linearly with feedback resistance. So best signal-to-noise ratio is achieved with large feedback resistance. This comes with the trade-off of decreased bandwidth.

The noise performance of a photodetector is sometimes characterized by Noise Effective Power (NEP). This is the radiant power which would produce an output signal equal to the noise level. NEP has the units of radiant power (watts). The typical performance curve “Noise Effective Power vs Measurement Bandwidth” shows how NEP varies with R_F and measurement bandwidth.

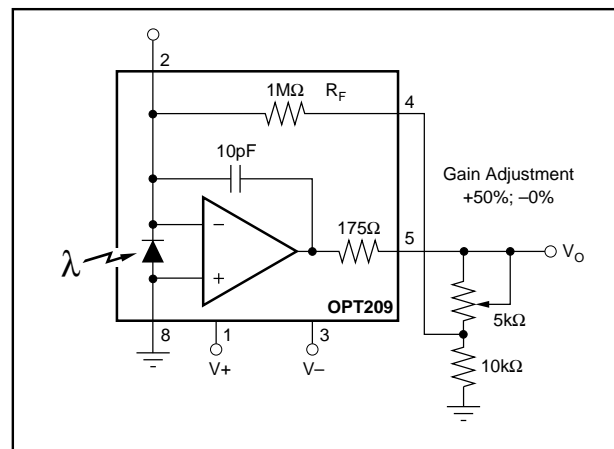


FIGURE 4. Responsivity (Gain) Adjustment Circuit.

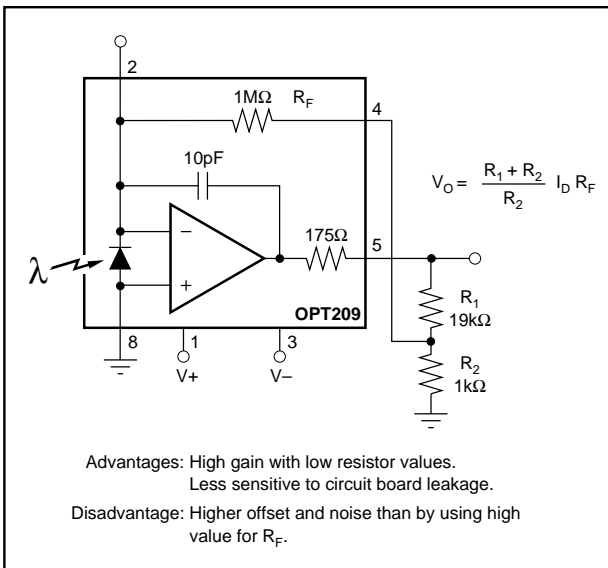


FIGURE 5. "T" Feedback Network.

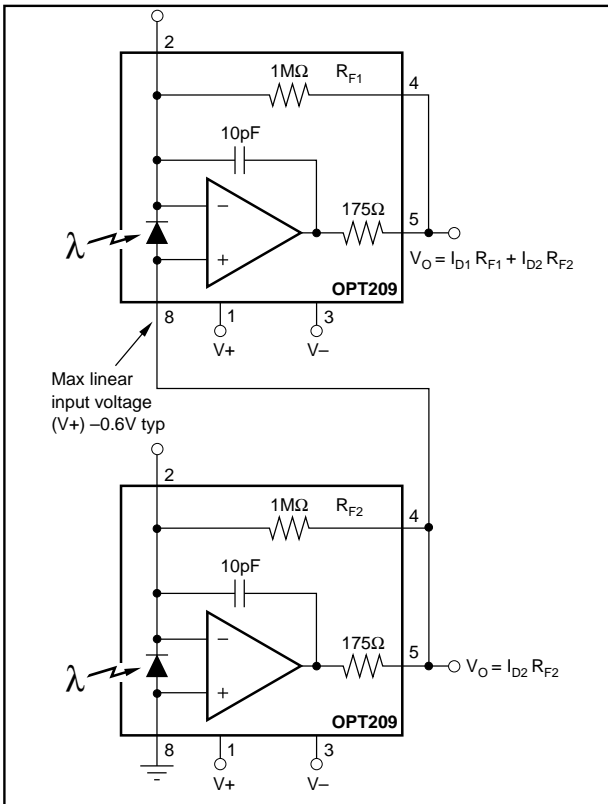


FIGURE 6. Summing Output of Two OPT209s.

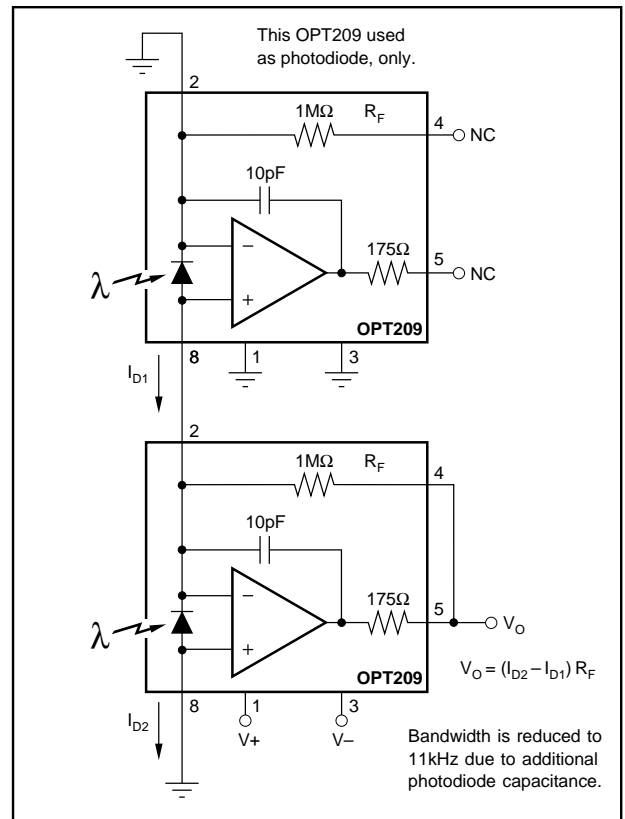


FIGURE 7. Differential Light Measurement.

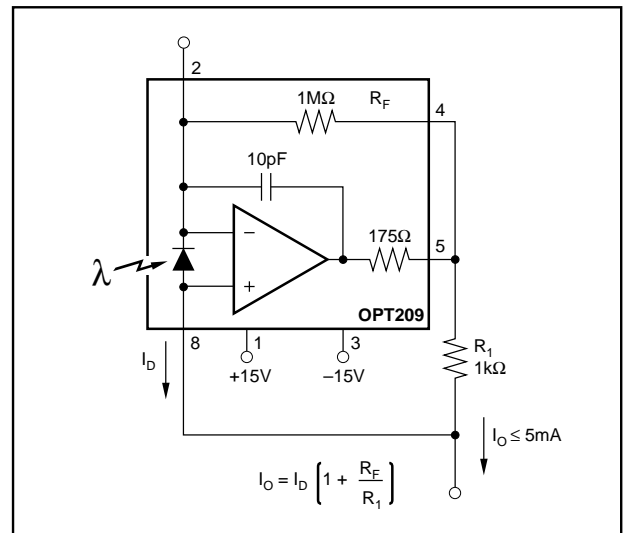


FIGURE 8. Current Output Circuit.

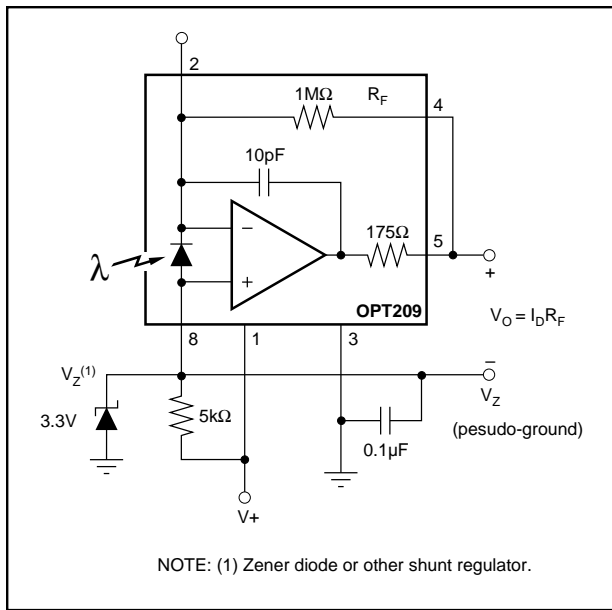


FIGURE 9. Single Power Supply Operation.

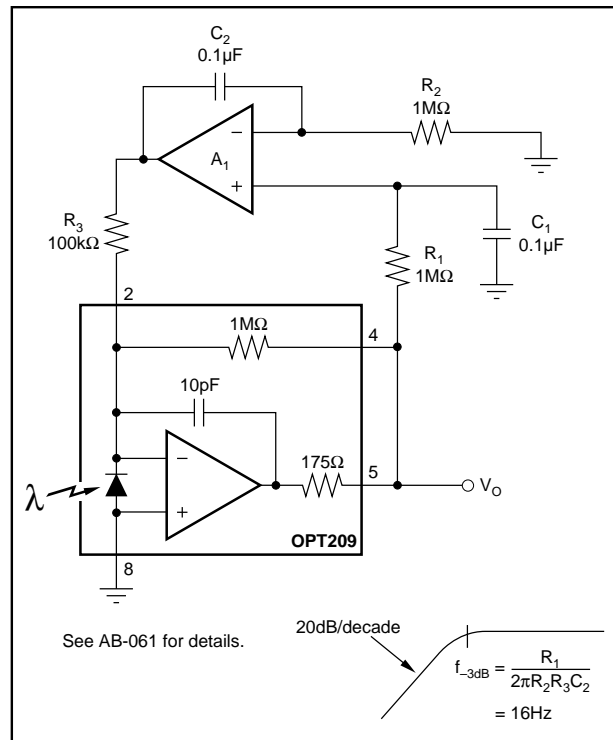


FIGURE 10. DC Restoration Rejects Unwanted Steady-State Background Light.

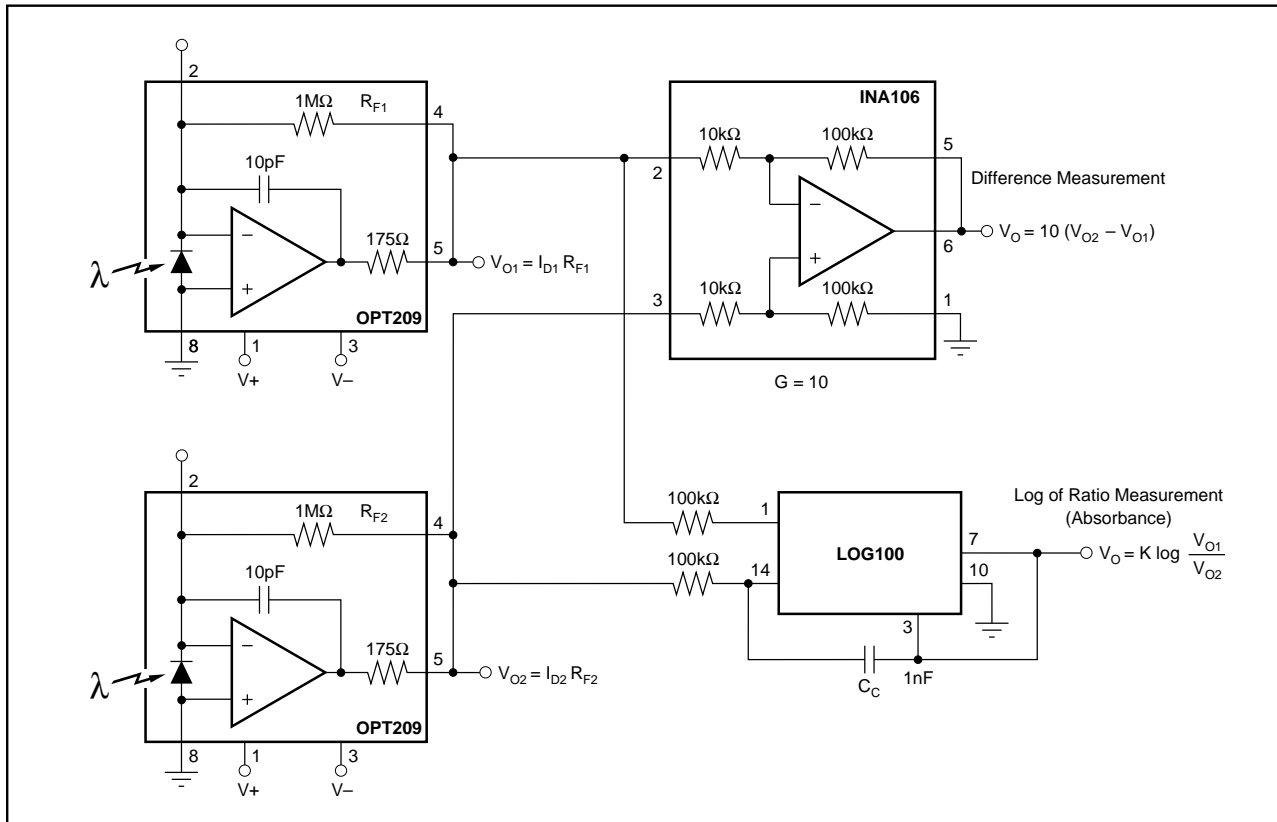


FIGURE 11. Differential Light Measurement.

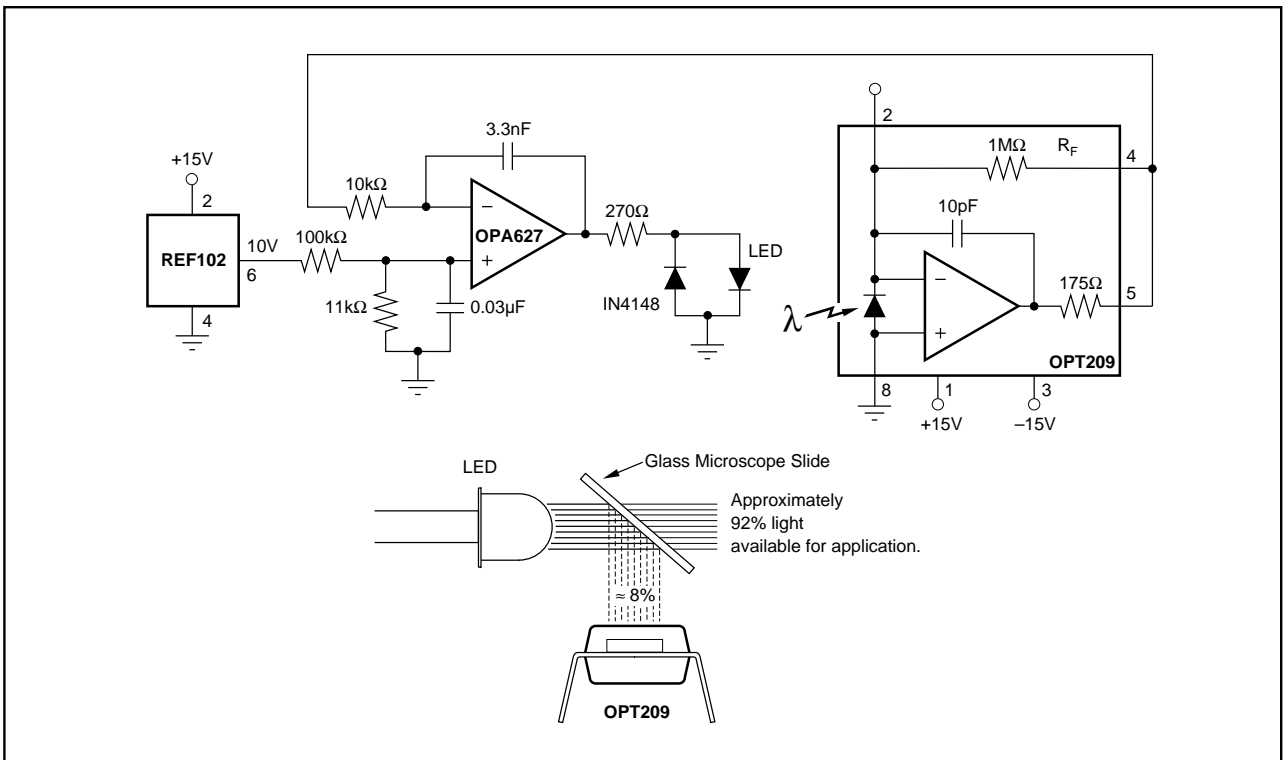


FIGURE 12. LED Output Regulation Circuit.

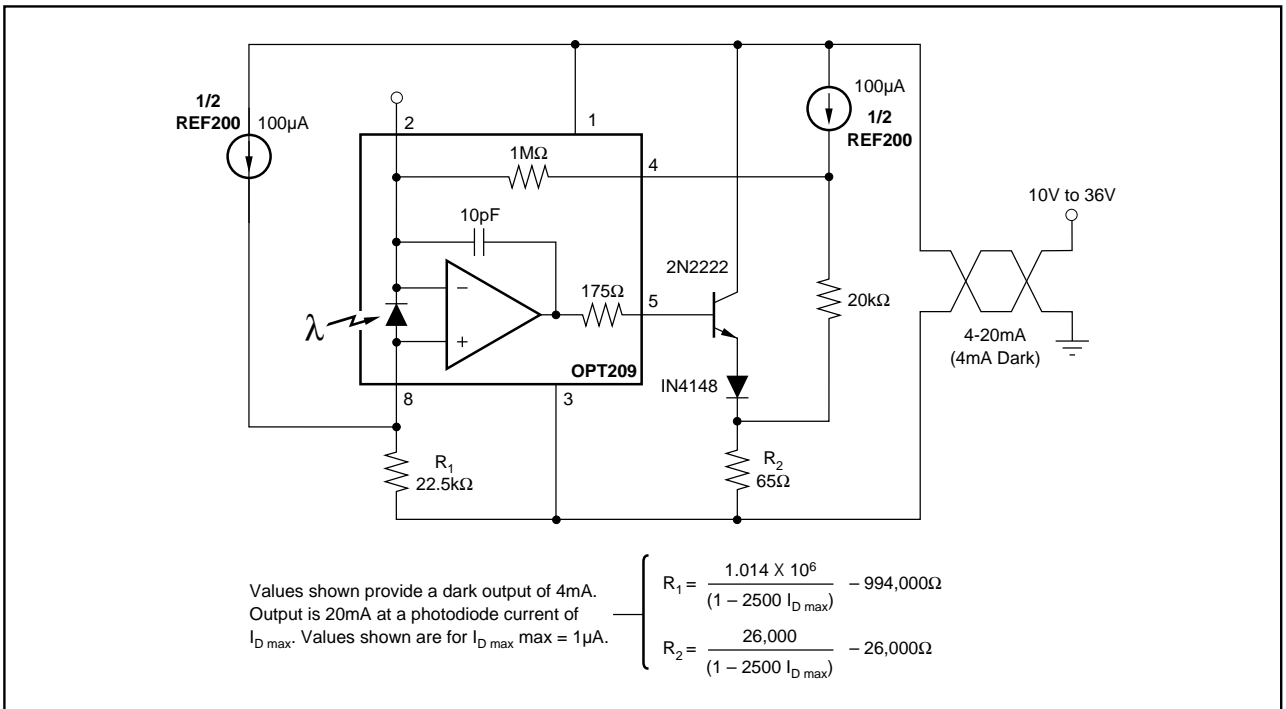
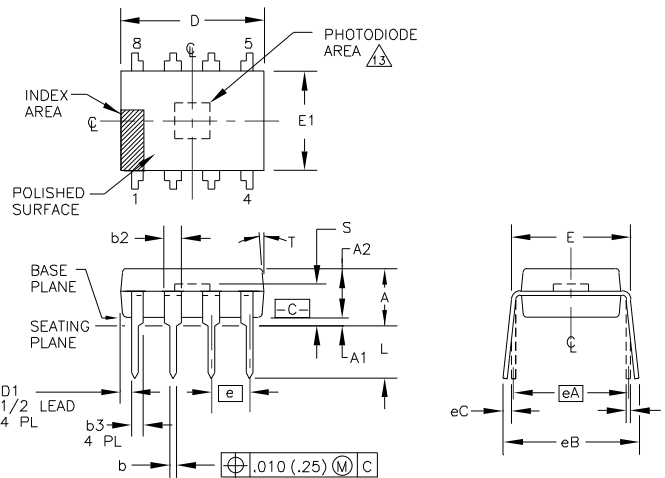


FIGURE 13. 4-20mA Current-Loop Transmitter.

PACKAGE DRAWING

Package Number 006-1 - 8-Pin Transparent Plastic Single-Wide DIP



DIM	INCHES		MILLIMETERS		N	E	DIM	INCHES		MILLIMETERS		N	E	NOTES:
	MIN.	MAX.	MIN.	MAX.				MIN.	MAX.	MIN.	MAX.			
A	--	.165	--	4.19	3		eC	.000	.060	0.00	1.52	6		<p>1. ALL DIMENSIONS ARE IN INCHES.</p> <p>2. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M-1982.</p> <p>3. DIMENSIONS A, A1, AND L ARE MEASURED WITH THE PACKAGE SEATED IN JEDEC SEATING PLANE GAUGE GS-3.</p> <p>4. D, D1, AND E1 DIMENSIONS DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED .010 (0.25mm).</p> <p>5. E AND eA MEASURED WITH THE LEADS CONSTRAINED TO BE PERPENDICULAR TO DATUM $\overline{-C-}$.</p> <p>6. eB AND eC ARE MEASURED AT THE LEAD TIPS WITH THE LEADS UNCONSTRAINED.</p> <p>7. N IS THE MAXIMUM OF TERMINAL POSITIONS.</p> <p>8. POINTED OR ROUNDED LEAD TIPS ARE PREFERRED TO EASE INSERTION.</p> <p>9. b2 AND b3 MAXIMUM DIMENSIONS DO NOT INCLUDE DAMBAR PROTRUSIONS. DAMBAR PROTRUSIONS SHALL NOT EXCEED .010 (0.25mm).</p> <p>10. DISTANCE BETWEEN LEADS INCLUDING DAMBAR PROTRUSIONS TO BE .005 (0.13mm) MINIMUM.</p> <p>11. A VISUAL INDEX FEATURE MUST BE LOCATED WITHIN CROSS-HATCHED AREA.</p> <p>12. FOR AUTOMATIC INSERTION, ANY RAISED IRREGULARITY ON THE TOP SURFACE (STEP, MESA, ETC.) SHALL BE SYMMETRICAL ABOUT THE LATERAL AND LONGITUDINAL PACKAGE CENTERLINES.</p> <p>\triangle CENTER OF PHOTODIODE MUST BE WITHIN .010 (0.25mm) OF CENTER OF PHOTODIODE AREA.</p>
A1	.015	--	0.38	--	3		L	.115	.160	2.92	4.06	3		
A2	.120	.135	3.05	3.43			N	8	8			7		
b	.014	.022	0.36	0.56			S	.100	.120	2.54	3.05			
b2	.040	.050	1.02	1.27	9		T	5.5'	8.5'	5.5'	8.5'			
b3	.030	.045	0.762	1.143	9									
c	.008	.015	0.20	0.38										
D	.360	.390	9.14	9.91	4									
D1	.005	--	0.13	--	4									
E	.300	.325	7.62	8.26	5									
E1	.238	.275	6.05	6.99	4									
e	.100	BASIC	2.54	BASIC										
eA	.300	BASIC	7.63	BASIC	5									
eB	--	.430	--	10.92	6									

PACKAGE NUMBER: Z2006-1 REV.: D
JEDEC NUMBER: NONE